

Conference panel will discuss China, India, Mexico and Vietnam

SAN JOSE—An expert panel at the fifth annual International Wafer-Level Packaging Conference will discuss the challenges and opportunities for semiconductor-related businesses and outsourcing in China, India, Mexico and Vietnam. [iwlpc.org]

The panel, “Where in the World?” will meet on October 16, the final day of the Conference, from 8-9:30 a.m. in the Wyndham Hotel, the Conference venue. Each of four speakers will explore the merits of four countries that are potentially pivotal to the semiconductor industry’s growth.



Bagla



Jones



Pausa



Rozakis

The panelists are, **Gunjan Bagla, India; Ron Jones, Mexico; Clements E. (Ed) Pausa, China; and Harry Rozakis, who will discuss the prospects for Vietnam. Each speaker brings extensive ex-**

perience with manufacturing in his specific country to the panel.

Bagla is a management consultant who helps Western companies succeed in India. His firm, Amritt, serves clients in the United States, Canada, and Western Europe in marketing to India, buying from India, and starting and running Indian operations.

He is the author of *Doing Business in 21st Century India: How to Profit Today from Tomorrow's Most Exciting Market*, to be published by Warner/Grand Central on July 31. Bagla earned a bachelor's degree in mechanical engineering from the Indian Institute of Technology, Kanpur, and an MBA with honors from Southern Illinois University, Edwardsville.

Ron Jones is co-founder and co-chairman of Silicon Border, which is establishing a high-tech science park in Mexico. Earlier, he was CEO of N-Able Group International.

Jones is a semiconductor industry veteran and an expert on outsourcing. He has spent four decades with companies that include Amkor Technology and Texas Instruments.

Clements E. (Ed) Pausa is a semiconductor packaging veteran of 48 years and is currently a director of the **Center for Technology and Innovation** for PriceWaterhouseCoopers LLP, an international professional services company.

He is also one of the key authors of PWC's special report, *China's Impact on the Semiconductor Industry*. During his extensive industry career, he held several management posts at National Semiconductor Corp., including vice president for international manufacturing and services.

Harry Rozakis, who will speak on current opportunities in Vietnam, has spent 30 years in the semiconductor packaging industry. He is the former president of ASAT Holdings, a major provider of IC assembly and packaging, and has held top management positions at several other IC packaging foundries.

His experience includes service with the former Hyundai IC packaging group, which he later renamed ChipPAC (now STATS ChipPAC) and developed into a major provider of assembly, packaging and test. He is currently establishing an IC packaging foundry in Vietnam.

This panel is free to all registrants and exhibitors at the Conference, which runs from Oct. 13-16. [iwlpc.org].